ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pa	PC. Bannockl	burn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarati the declaration e	on of the su	ibstances v s all lower	within the manufactu level materials for w	rer listed i which the r	tem. Note: nanufacture	if the item is an as r has engineering	sembly with low responsibility.	
	P1.1IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175xFor Dis				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					tion				
upplier Information														
Company name* Compan			ipany unique ID			Unique ID Authority				Respon	Response Date*			
isemi											2024-05-14			
Contact Name	act Name Title - Contact				Phone - Contact*				Email - Contact*					
roduct-Env-Stewards Product Envir			iro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative			sentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product E			luct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	M	Ianufacturing Site		Weight*	UOM	Unit Type	
	NRVHP	NRVHP420MFDT3G 200V/2A PUF		DFN-8		2024-05-14		M	MY1		89.49	mg	Each	
Ianufacturing Proccess Informa	tion		•											
Terminal Plating / Grid Array M	aterial	Ferminal Base A	Alloy	J-STD-020 MSL Rating		Peak Proce	ak Process Body Temperatu		ure Max Time at Peak Temper		ture Num	ber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	secor	nds 3			
omments														
vel 1 - maximum time at peak temperat	ure during so	dering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	0.34	mg	Supplier	Zinc (Zn)	7440-66-6		0.0004	mg
			Supplier	Iron (Fe)	7439-89-6		0.008	mg
			Supplier	Copper (Cu)	7440-50-8		0.3315	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0001	mg
Die	1.66	mg	Supplier	Silicon (Si)	7440-21-3		1.66	mg
Die Attach Solder	3.08	mg	Supplier	Silver (Ag)	7440-22-4		0.077	mg
			А	Lead (Pb)	7439-92-1	7a	2.849	mg
			Supplier	Tin (Sn)	7440-31-5		0.154	mg
Lead Frame	37.39	mg	Supplier	Silver (Ag)	7440-22-4		0.3739	mg
			Supplier	Iron (Fe)	7439-89-6		0.0374	mg
			Supplier	Copper (Cu)	7440-50-8		36.9675	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0112	mg
Mold Compound-Black	45.37	mg		Epoxy resin	proprietary data		3.4028	mg
			Supplier	Phenolic Resin	Proprietary Data		1.1343	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.4028	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2268	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		37.2034	mg
Plating	1.56	mg	Supplier	Tin (Sn)	7440-31-5		1.56	mg
Wire Bond - Cu	0.09	mg	Supplier	Copper (Cu)	7440-50-8		0.09	mg